# LumiDLP<sup>™</sup> 3300B Modular Illuminator

#### **Features**

- UV Powers of 25-35 Watts (18 die array)
- Designs for Large Format TI DLP<sup>™</sup>
   Chipsets
- Non-imaging Etendue Preserving Optics
- Bi-telecentric Lens System
- Recirculating Liquid Heat Exchanger
- Field Replaceable Light Engine FRU





#### **Applications**

#### **Industrial**

- Direct imaging Lithography
- Laser Markings and Repair Systems
- Computer to Plate Printers
- Rapid Prototype Machines
- 3D Printers

#### Medical

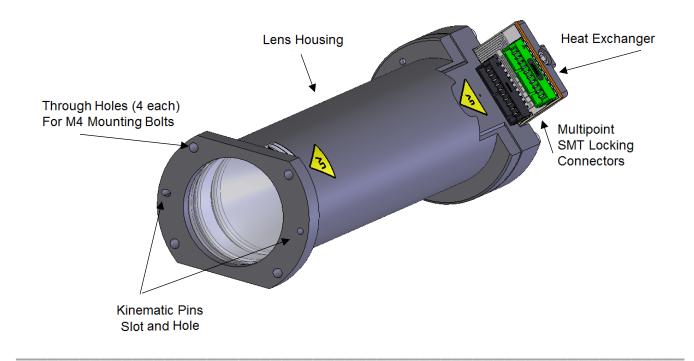
- Ophthalmology
- Photo Therapy
- Hyperspectral Imaging

The LumiDLP<sup>TM</sup> Illuminator allows unprecedented speed and resolution for Ultraviolet DLP applications by providing highly uniform flux density over large areas. The patented, modular device couples a densely packed UV-LED array to a high efficiency, non-imaging collection optic integrated with a telecentric imaging optic optimized to the DLP chipset.

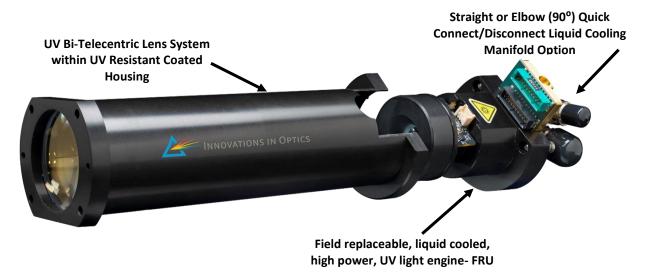
The LumiDLP<sup>™</sup> is sold as a kit, including the optics module and a driver. The optics module is easily mounted with kinematic registration on a flange mount. The field replaceable unit (FRU) provides fast, easy light engine replacement with no need for re-alignment or adjustment.



#### **LumiDLP**<sup>TM</sup> – Illuminator Assembly



### **Modular Design for Field Serviceability**

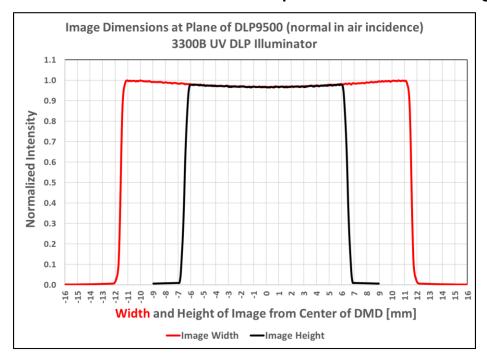


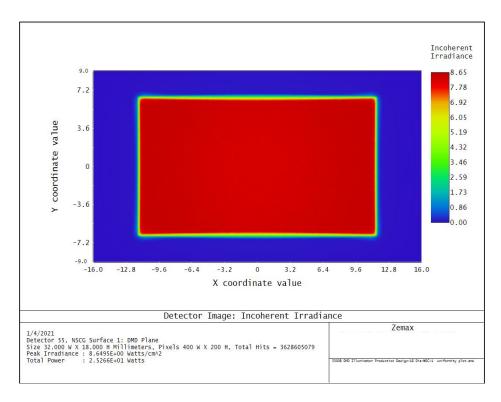
- Field Replaceable Unit (FRU) is pre-aligned, calibrated, with quick disconnects for coolant
- Provides fast, easy replacement with no need for re-alignment or adjustment



## **LumiDLP™** – Excellent Spatial Uniformity

- LumiDLP<sup>™</sup> optical design provides highly uniform flux density over large areas
- Radiant flux is confined to 12° acceptance half-angle and DLP active area
- Illumination overfill of the DLP relaxes positional tolerances along optical axis

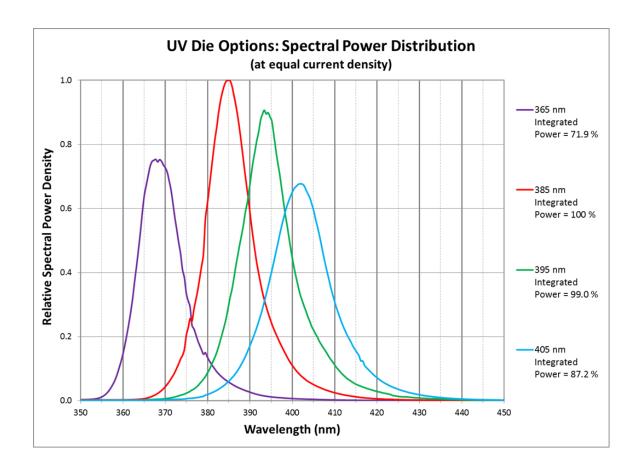






# **LumiDLP™ UV LED Die Options for 3300B**

- LED die are available in a range of UV and Violet wavelengths
- For example Mercury Xenon Lamp
  - 365nm i-line
  - 405nm h-line
- Mix of die is ideal for thicker UV resists
- Array can be populated to fit your needs



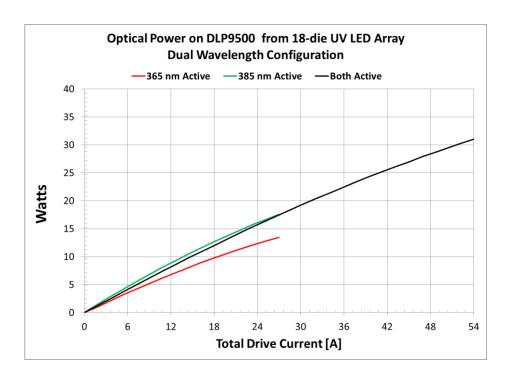


## **LumiDLP™ Total Flux – Single Wavelength**



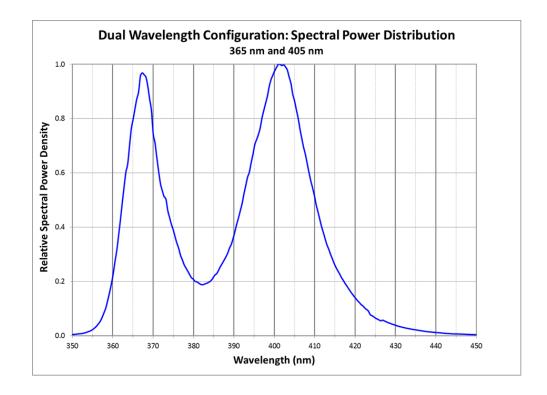
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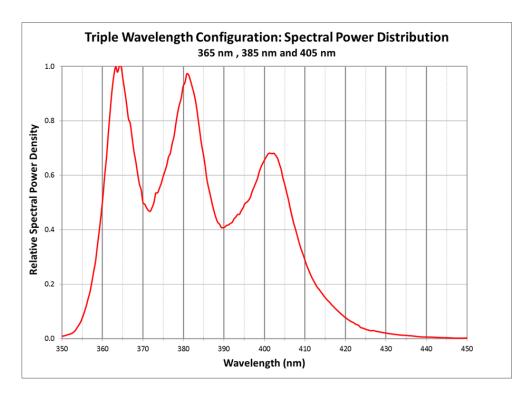
## **LumiDLP™** Total Flux – Dual Wavelength Configuration





## **LumiDLP<sup>TM</sup> Wavelength Combination Options**





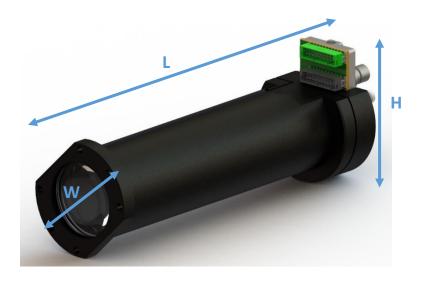


# **LumiDLP<sup>TM</sup> Specifications**

PARAMETER	SPECIFICATION	COMMENT
Optical power output at 3 amps drive current	≥ 35 Watts	18 die array
Drive current per channel / die	Min 0.30 Amps Max 3.0 Amps	Continuous operation. Die can be driven individually.
Available wavelength bins	365 – 405nm	Contact Sales Engineer
Output numerical aperture	NA=0.208	Matches DLP +/- 12°micromirror tilt angle
Numerical aperture overfill	+/- 10%	Peak-to-peak (P-P)
Electrical power input	300W	Typical Maximum
Operating environment	15°C to 35°C	5% to 85%, relative humidity, non- condensing
Thermal impedance	10 kΩ	At 25° C
Thermistor B <sub>25/85</sub>	3574-3646	For 10 kΩ
Cooler Fittings	Quick Disconnect/No Spill	Right angle (articulating) or In-line
Liquid Cooling Supply	Use in-line filter on inlet	Must be 20 μm rating
Mounting Flange	Four through holes on 68mm diameter	10mm depth for M4 bolts
	Kinematic Hole/Slot	Locks position/rotation

# **LumiDLP<sup>TM</sup> Dimensions**

Length (L)	272.0 mm
Width (W)	76.0 mm
Height (H)	85.5 mm





#### **Multi-channel Driver/Controller 5500A Series**



#### **Features:**

- Single constant current source
- Uniform drive current across array for precise exposure control
- Up to 5A each for up to 18 UV-LED die (maximum recommended for LumiDLP™ is 3.0A per die)

#### **Connectivity:**

- Command set for Ethernet and Modbus serial communication
- External trigger

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